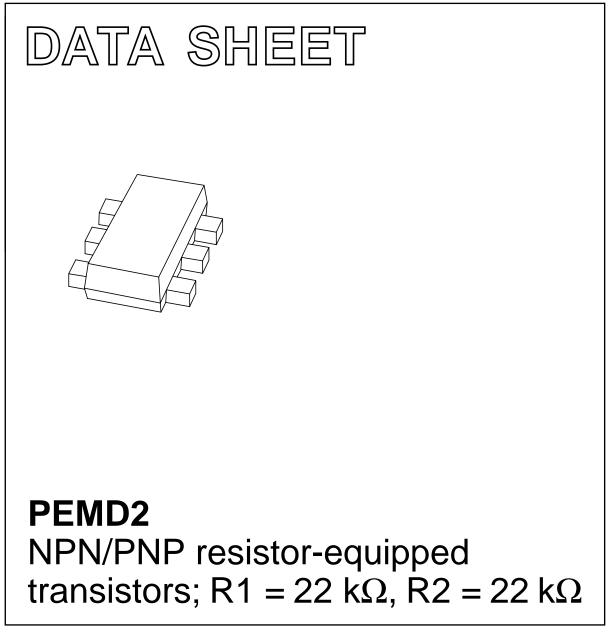
## DISCRETE SEMICONDUCTORS



Preliminary specification



## PEMD2

#### FEATURES

- 300 mW total power dissipation
- Very small 1.6 mm x 1.2 mm ultra thin package
- Self alignment during soldering due to straight leads
  Replaces two SC-75/SC-89 packaged transistors on same PCB area
- Reduces required PCB area
- Reduced pick and place costs.

#### **APPLICATIONS**

- General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

#### DESCRIPTION

NPN/PNP resistor-equipped transistors in a SOT666 plastic package.

#### MARKING

TYPE NUMBER	MARKING CODE		
PEMD2	D4		

## QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	50	V
I <sub>CM</sub>	peak collector current	100	mA
TR1	NPN	-	-
TR2	PNP	-	-
R1	bias resistor	22	kΩ
R2	bias resistor	22	kΩ

### PINNING

PIN	DESCRIPTION		
1, 4	emitter	TR1; TR2	
2, 5	base	TR1; TR2	
6, 3	collector	TR1; TR2	

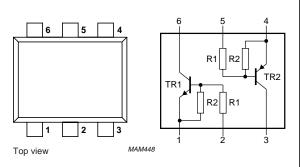


Fig.1 Simplified outline (SOT666) and symbol.

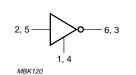


Fig.2 Equivalent inverter symbol.

## PEMD2

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transistor; for the PNP transistor with negative polarity					
V <sub>CBO</sub>	collector-base voltage	open emitter	-	50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	10	V
VI	input voltage TR1				
	positive		-	+40	V
	negative		-	-10	V
	input voltage TR2				
	positive		-	+10	V
	negative		-	-40	V
I <sub>O</sub>	output current (DC)		-	100	mA
I <sub>CM</sub>	peak collector current		-	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	200	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C
Per device					•
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	300	mW

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	notes 1 and 2	416	K/W	

#### Notes

1. Transistor mounted on an FR4 printed-circuit board.

2. The only recommended soldering method is reflow soldering.

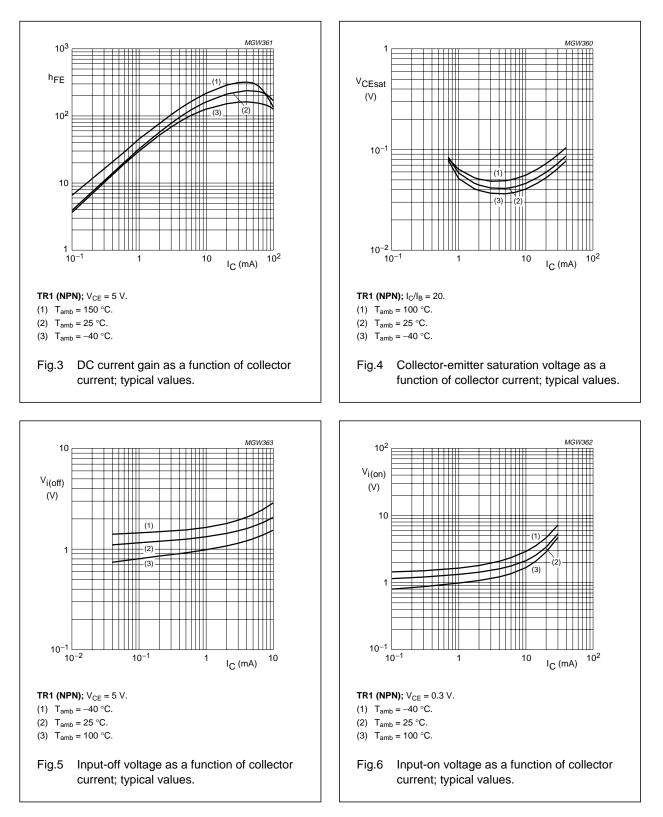
## PEMD2

## CHARACTERISTICS

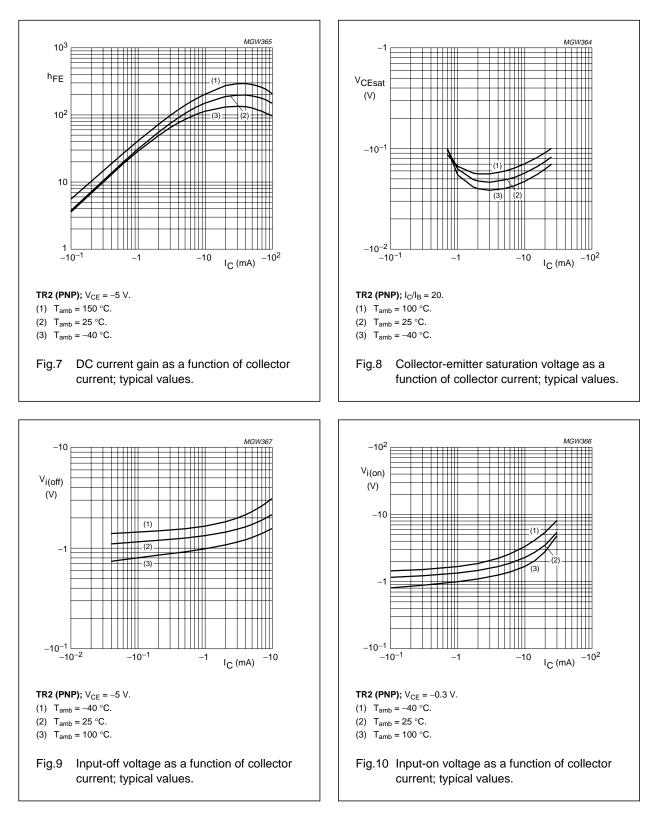
 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transist	or; for the PNP transistor with ne	gative polarity				
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = 50 \text{ V}; \text{ I}_{E} = 0$	-	-	100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = 50 \text{ V}; \text{ I}_{B} = 0$	-	-	1	μA
		$V_{CE} = 30 \text{ V}; \text{ I}_{B} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$	-	-	50	μA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 5 V; I_C = 0$	-	-	180	μA
h <sub>FE</sub>	DC current gain	$V_{CE} = 5 V; I_C = 5 mA$	60	-	-	
V <sub>CEsat</sub>	saturation voltage	I <sub>C</sub> = 10 mA; I <sub>B</sub> = 0.5 mA	-	-	150	mV
V <sub>i(off)</sub>	input off voltage	$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 100 \mu\text{A}$	-	1.1	0.8	V
V <sub>i(on)</sub>	input on voltage	$V_{CE} = 0.3 \text{ V}; I_{C} = 5 \text{ mA}$	2.5	1.7	-	V
R <sub>1</sub>	input resistor		15.4	22	28.6	kΩ
R2 R1	resistor ratio		0.8	1	1.2	
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0; V_{CB} = 10 V;$				
	TR1 (NPN)	f = 1 MHz	-	-	2.5	pF
	TR2 (PNP)		-	-	3	pF

## PEMD2



## PEMD2



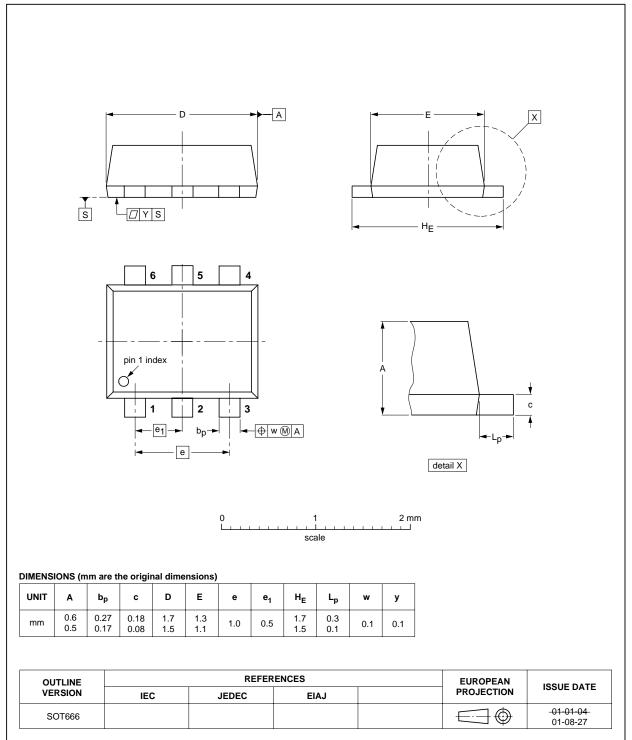
PEMD2

SOT666

## NPN/PNP resistor-equipped transistors; R1 = 22 k $\Omega$ , R2 = 22 k $\Omega$

## PACKAGE OUTLINE

## Plastic surface mounted package; 6 leads



## PEMD2

#### DATA SHEET STATUS

DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

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